

TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

SSM3K36MFV

O High-Speed Switching Applications

Unit: mm

1. Features

• 1.5-V drive

Low ON-resistance: Ron = 1.52 Ω (max) (@VGS = 1.5 V)

: Ron = 1.14 Ω (max) (@VGS = 1.8 V)

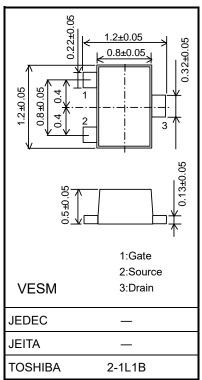
: Ron = 0.85Ω (max) (@VGS = 2.5 V)

: Ron = 0.66Ω (max) (@VGS = 4.5 V)

: Ron = 0.63Ω (max) (@VGS = 5.0 V)

2. Absolute Maximum Ratings (Note) (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		VDSS	20	V	
Gate-source voltage		Vgss	± 10	V	
Drain current	DC	ΙD	500	mA	
	Pulse	IDP	1000		
Drain power dissipation		P _D (Note 1)	150	mW	
Channel temperature		T _{ch}	150	°C	
Storage temperature		T _{stg}	-55 to 150	°C	



Weight: 1.5 mg (typ.)

Note: Using continuously under heavy loads (e.g. the application of high

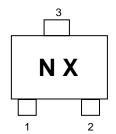
temperature/current/voltage and the significant change in temperature,

etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

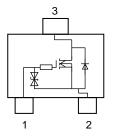
Note1: Mounted on an FR4 board

 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ mm}, \text{Cu Pad: } 0.585 \text{ mm}^2)$

3. Marking



4. Equivalent Circuit (Top view)



Start of commercial production 2008-02

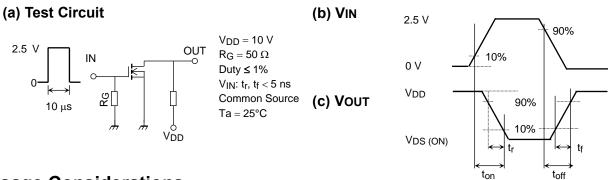


4. Electrical Characteristics (Ta = 25°C)

Chara	acteristics	Symbol	Test Conditions	Min	Тур.	Max	Unit
Duning and was also been supplied to	V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	20	_		· V	
Drain-source breakdown voltage		V (BR) DSX	I _D = 1 mA, V _{GS} = - 10 V	12	_		
Drain cutoff current		I _{DSS}	V _{DS} =20 V, V _{GS} = 0 V	_	_	1	μΑ
Gate leakage curre	ent	IGSS	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μΑ
Gate threshold vol	tage	V _{th}	$V_{DS} = 3 \text{ V}, I_D = 1 \text{ mA}$	0.35	_	1.0	V
Forward transfer a	dmittance	Y _{fs}	$V_{DS} = 3 \text{ V}, I_{D} = 200 \text{ mA}$ (Note2)	420	840	_	mS
Drain-source ON-resistance	Rds (ON)	I _D = 200 mA, V _{GS} = 5.0 V (Note2)	_	0.46	0.63	Ω	
		I _D = 200 mA, V _{GS} = 4.5 V (Note2)	_	0.51	0.66		
		I _D = 200 mA, V _{GS} = 2.5 V (Note2)	_	0.66	0.85		
		I _D = 100 mA, V _{GS} = 1.8 V (Note2)	_	0.81	1.14		
		I _D = 50 mA, V _G S = 1.5 V (Note2)	_	0.95	1.52		
Input capacitance Output capacitance		C _{iss}		_	46	_	pF
		Coss	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	10.8	_	
Reverse transfer capacitance		Crss		_	7.3	_	
Total Gate Charge Gate–Source Charge		Qg		_	1.23	_	nC
		Qgs	V _{DS} = 10V, I _D = 0.5 A, V _{GS} = 4.0 V	_	0.60	_	
Gate-Drain Charge		Q _{gd}		_	0.63	_	
Switching time	Turn-on time	ton	V _{DD} = 10 V, I _D = 200 mA	_	30	_	ns
	Turn-off time	t _{off}	$V_{GS} = 0$ to 2.5 V, $R_{G} = 50 \Omega$	_	75		
Drain-source forward voltage		VDSF	I _D = -0.5 A, V _G S = 0 V (Note2)	_	-0.88	-1.2	V

Note2: Pulse test

5. Switching Time Test Circuit



Usage Considerations

Let Vth be the voltage applied between gate and source that causes the drain current (ID) to below (1 mA for the SSM3K36MFV). Then, for normal switching operation, VGS(on) must be higher than Vth, and VGS(off) must be lower than Vth. This relationship can be expressed as: VGS(off) < Vth < VGS(on).

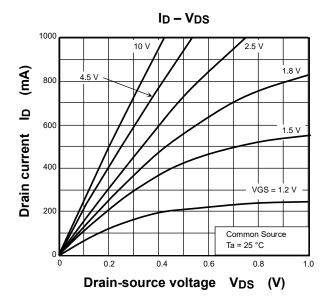
Take this into consideration when using the device.

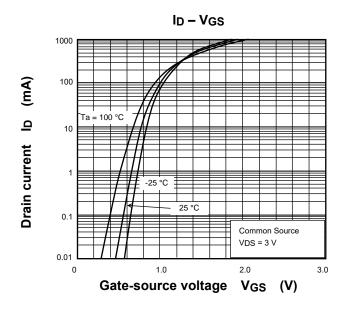
Handling Precaution

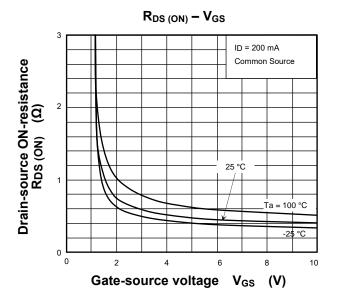
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

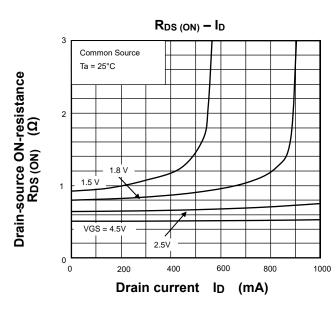


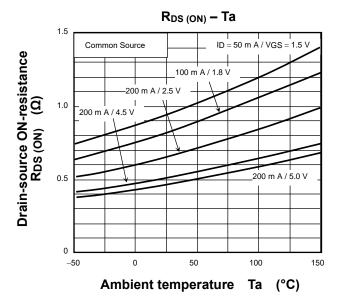
6. Characteristics Curves (Note)

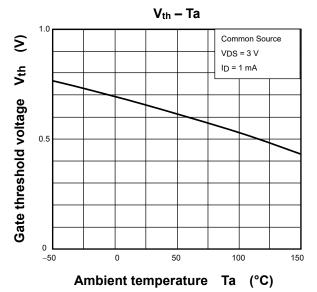




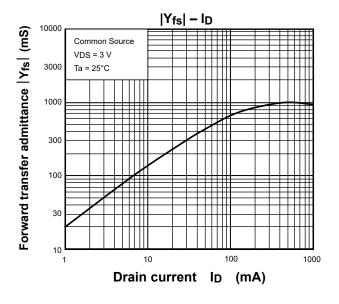


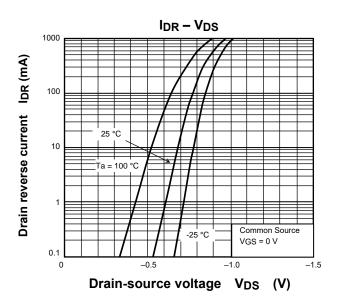


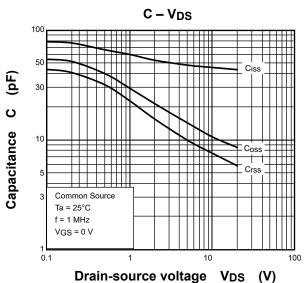


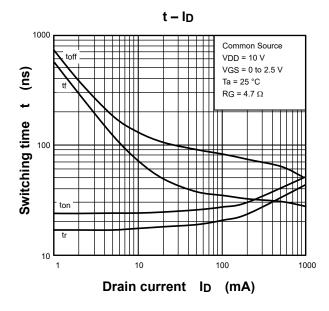


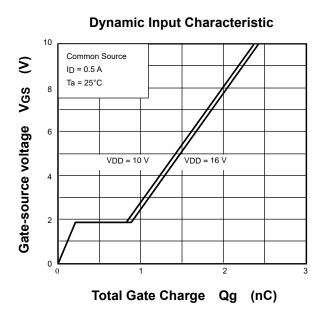


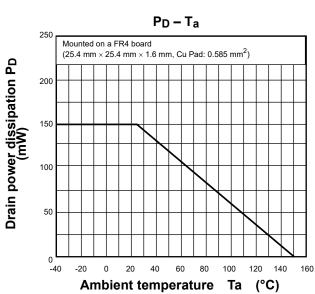












Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



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